



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20230712003.0  
Marking Standardization for Select Devices  
Information Only**

**Date:** July 13, 2023

**To:** Digi-Key PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team  
SC Business Services

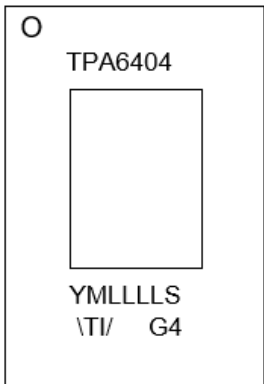
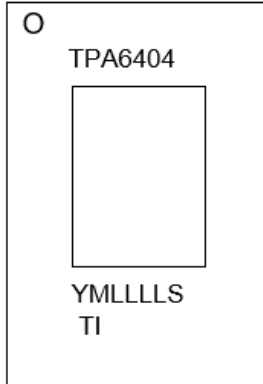
**20230712003.0**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TAS3251DKQ	null
TAS3251DKQR	null
TAS6421QDKQRQ1	null
TAS6422EQDKQRQ1	null
TAS6422QDKQQ1	null
TAS6424LQDKQQ1	null
TAS6424MSQDKQRQ1	null
TAS6424QDKQQ1	null
TAS6424QDKQRQ1	null
TPA6404QDKQQ1	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20230712003.0		<b>PCN Date:</b>	July 13, 2023	
<b>Title:</b>	Marking Standardization for Select Devices				
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services	
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Materials
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
This notice is to communicate an update in the device symbolization format for the devices in the product affected selection as follows:					
<b>Package Device</b>					
	<b>Current</b>		<b>Proposed</b>		
	 <p>\TI/ = TI LOGO YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR</p>		 <p>TI = TI LETTER YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR</p>		
TI Logo	With		TI letter		
**ECAT value	G4		None		
** - Not all devices have ECAT information included in the symbolization, but for the ones that do, this information will be removed.					
<b>Reason for Change:</b>					
Marking Standardization					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Changes to product identification resulting from this PCN:</b>					
None					
<b>Product Affected:</b>					
PSN6402HWQDKQRQ1	SN1911043DKQR	TAS6424HSQDKQRQ1	TAS6424RHQDKQRQ1		
PTAS6422QDKQRQ1	SN1911053DKQR	TAS6424LQDKQQ1	TAS6424RQDKQRQ1		
PTAS6424HSQDKQRQ1	SN6402HWQDKQRQ1	TAS6424LQDKQRQ1	TPA6402VQDKQQ1		

PTAS6424LQDKQQ1	SN6424LFQDKQRQ1	TAS6424LSQDKQQ1	TPA6402VQDKQRQ1
PTAS6424LQDKQRQ1	TAS3251DKQ	TAS6424LSQDKQRQ1	TPA6404QDKQQ1
PTAS6424MQDKQQ1	TAS3251DKQR	TAS6424MQDKQQ1	TPA6404QDKQRQ1
PTAS6424MQDKQRQ1	TAS6421QDKQRQ1	TAS6424MQDKQRQ1	TPA6414QDKQQ1
PTAS6424MSQDKQRQ1	TAS6422EQDKQRQ1	TAS6424MSQDKQRQ1	TPA6414QDKQRQ1
PTAS6424RHQDKQRQ1	TAS6422QDKQQ1	TAS6424QDKQQ1	
PTAS6424RQDKQRQ1	TAS6422QDKQRQ1	TAS6424QDKQRBO	
PTPA6414QDKQRQ1	TAS6424EQDKQRQ1	TAS6424QDKQRQ1	

ZVEI ID reference: SEM-PA-13

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.